

1.8V, 7MHz, 90dB CMRR, Single-Supply, Rail-to-Rail I/O Operational Amplifier

Check for Samples: [OPA363](#), [OPA2363](#), [OPA364](#), [OPA2364](#), [OPA4364](#)

FEATURES

- 1.8V Operation
- *MicroSize* Packages
- Bandwidth: 7MHz
- CMRR: 90dB (typical)
- Slew Rate: 5V/μs
- Low Offset: 500μV (max)
- Quiescent Current: 750μA/Channel (max)
- Shutdown Mode: < 1μA/Channel

APPLICATIONS

- Signal Conditioning
- Data Acquisition
- Process Control
- Active Filters
- Test Equipment

DESCRIPTION

The OPA363 and OPA364 families are high-performance CMOS operational amplifiers optimized for very low voltage, single-supply operation. These miniature, low-cost amplifiers are designed to operate on single supplies from 1.8V (±0.9V) to 5.5V (±2.75V). Applications include sensor amplification and signal conditioning in battery-powered systems.

The OPA363 and OPA364 families offer excellent CMRR without the crossover associated with traditional complimentary input stages. This results in excellent performance for driving Analog-to-Digital (A/D) converters without degradation of differential linearity and THD. The input commonmode range includes both the negative and positive supplies. The output voltage swing is within 10mV of the rails.

The OPA363 family includes a shutdown mode. Under logic control, the amplifiers can be switched from normal operation to a standby current that is less than 1μA.

The single version is available in the *MicroSize* SOT23-5 (SOT23-6 for shutdown) and SO-8. The dual version is available in MSOP-8, MSOP-10, UQFN-16, and SO-8 packages. Quad packages are available in TSSOP-14 and SO-14 packages. All versions are specified for operation from –40°C to +125°C.

| | OPA363 | OPA364 | OPA2363 | OPA2364 | OPA4364 |
|----------|--------|--------|---------|---------|---------|
| SOT23-5 | | X | | | |
| SOT23-6 | X | | | | |
| MSOP-8 | | | | X | |
| MSOP-10 | | | X | | |
| SO-8 | X | X | | X | |
| TSSOP-14 | | | | | X |
| SO-14 | | | | | X |
| UQFN-16 | | | X | | |



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE AND ORDERING INFORMATION⁽¹⁾

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or visit the device product folder at www.ti.com.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Over operating free-air temperature range, unless otherwise noted.

| | | VALUE | UNIT |
|---------------------------------------|------------------------|--------------------|------|
| Supply voltage | | +5.5 | V |
| Signal input terminals | Voltage ⁽²⁾ | -0.5 to (V+) + 0.5 | V |
| | Current ⁽²⁾ | ±10 | mA |
| Output short-circuit ⁽³⁾ | | Continuous | mA |
| Operating temperature, T _A | | -40 to +150 | °C |
| Storage temperature, T _{stg} | | -65 to +150 | °C |
| Junction temperature, T _J | | +150 | °C |

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.
- (3) Short-circuit to ground, one amplifier per package.

ELECTRICAL CHARACTERISTICS: V_S = +1.8V to +5.5V

Boldface limits apply over the specified temperature range, T_A = -40°C to +125°C.

At T_A = +25°C, R_L = 10kΩ connected to V_S/2, V_{OUT} = V_S/2, and V_{CM} = V_S/2, unless otherwise noted.

| PARAMETER | CONDITIONS | OPAx363, OPAx364 | | | UNIT |
|--|---|---|-----------|------------|------------------|
| | | MIN | TYP | MAX | |
| OFFSET VOLTAGE | | | | | |
| Input Offset Voltage, OPA363I, OPA364I OPA2363I, OPA2364I | V _{OS} V _S = +5V | | | 500 | μV |
| OPA363AI, OPA364AI, OPA2363AI, OPA2364AI, OPA4364AI | | | 1 | 2.5 | mV |
| Drift | dV_{OS}/dT | | 3 | | μV/°C |
| vs Power Supply | PSRR | V_S = 1.8V to 5.5V, V_{CM} = 0 | 80 | 330 | μV/V |
| Channel Separation, dc | | | 1 | | μV/V |
| INPUT BIAS CURRENT | | | | | |
| Input Bias Current over Temperature | I _B | | ±1 | ±10 | pA |
| Input Offset Current | I _{OS} | | ±1 | ±10 | pA |
| NOISE | | | | | |
| Input Voltage Noise, f = 0.1Hz to 10Hz | e _n | | 10 | | μV _{PP} |
| Input Voltage Noise Density, f = 10kHz | e _n | | 17 | | nV/√Hz |
| Input Current Noise Density, f = 10kHz | i _n | | 0.6 | | fA/√Hz |
| INPUT VOLTAGE RANGE | | | | | |
| Common-Mode Voltage Range | V _{CM} | (V-) - 0.1 | | (V+) + 0.1 | V |
| Common-Mode Rejection Ratio | CMRR | (V-) - 0.1V < V_{CM} < (V+) + 0.1V | 74 | 90 | dB |

ELECTRICAL CHARACTERISTICS: $V_S = +1.8V$ to $+5.5V$ (continued)
Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+125^{\circ}C$.

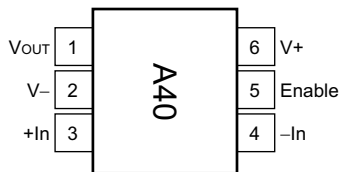
 At $T_A = +25^{\circ}C$, $R_L = 10k\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, and $V_{CM} = V_S/2$, unless otherwise noted.

| PARAMETER | CONDITIONS | OPAx363, OPAx364 | | | UNIT |
|-----------------------------------|---|---|------------|--------------|---------------------------|
| | | MIN | TYP | MAX | |
| INPUT CAPACITANCE | | | | | |
| Differential | | | 2 | | pF |
| Common-Mode | | | 3 | | pF |
| OPEN-LOOP GAIN | | | | | |
| Open-Loop Voltage Gain | $R_L = 10k\Omega$, $100mV < V_O < (V+) - 100mV$ | 94 | 100 | | dB |
| OPA4364AI | | 90 | | | dB |
| over Temperature | $V_S = 1.8V$ to $5.5V$ | 86 | | | dB |
| FREQUENCY RESPONSE | | | | | |
| Gain-Bandwidth Product | $C_L = 100pF$ | | 7 | | MHz |
| Slew Rate | $G = +1$ | | 5 | | V/ μs |
| Settling Time, 0.1% | $V_S = +5V$, 4V Step, $G = +1$ | | 1 | | μs |
| 0.01% | $V_S = +5V$, 4V Step, $G = +1$ | | 1.5 | | μs |
| Overload Recovery Time | $V_{IN} \cdot \text{Gain} > V_S$ | | 0.8 | | μs |
| Total Harmonic Distortion + Noise | $V_S = +5V$, $G = +1$, $f = 20kHz$ to $20kHz$ | | 0.002 | | % |
| OUTPUT | | | | | |
| Voltage Output Swing | $R_L = 10k\Omega$ | | 10 | 20 | V |
| Over Temperature | $R_L = 10k\Omega$ | | | 20 | V |
| Short-Circuit Current | I_{SC} | See Typical Characteristics | | | |
| Capacitive Load Drive | C_{LOAD} | See Typical Characteristics | | | |
| SHUTDOWN (for OPAx363) | | | | | |
| t_{OFF} | | | 1 | | μs |
| $t_{ON}^{(1)}$ | | | 20 | | μs |
| V_I (shutdown) | | | | $(V-) + 0.8$ | V |
| V_h (amplifier is active) | | 0.75 (V+) | | 5.5 | V |
| I_{QSD} | | | | 0.9 | μA |
| POWER SUPPLY | | | | | |
| Specified Voltage Range | V_S | 1.8 | | 5.5 | V |
| Operating Voltage Range | | | 1.8 to 5.5 | | V |
| Quiescent Current (per amplifier) | I_Q | $V_S = +1.8V$ | 650 | 750 | μA |
| | | $V_S = +3.6V$ | 850 | 1000 | μA |
| | | $V_S = +5.5V$ | 1.1 | 1.4 | mA |
| TEMPERATURE RANGE | | | | | |
| Specified Range | | -40 | | +125 | $^{\circ}C$ |
| Operating Range | | -40 | | +150 | $^{\circ}C$ |
| Storage Range | | -65 | | +150 | $^{\circ}C$ |
| Thermal Resistance | θ_{JA} | | | | |
| SOT23-5, SOT23-6 | | | 200 | | $^{\circ}C/W$ |
| MSOP-8, MSOP-10, SO-8 | | | 150 | | $^{\circ}C/W$ |
| TSSOP-14, SO-14 | | | 100 | | $^{\circ}C/W$ |

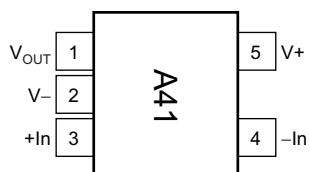
(1) Part is considered enabled when input offset voltage returns to specified range.

PIN CONFIGURATION

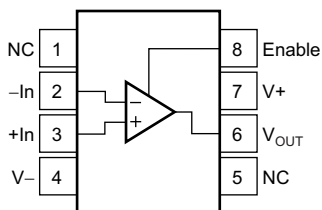
**OPA363⁽¹⁾: DBV PACKAGE
SOT23-6
(TOP VIEW)**



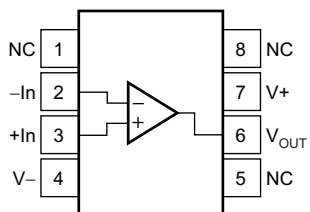
**OPA364⁽¹⁾: DBV PACKAGE
SOT23-5
(TOP VIEW)**



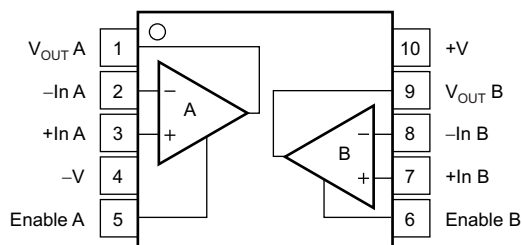
**OPA363: D PACKAGE
SO-8
(TOP VIEW)**



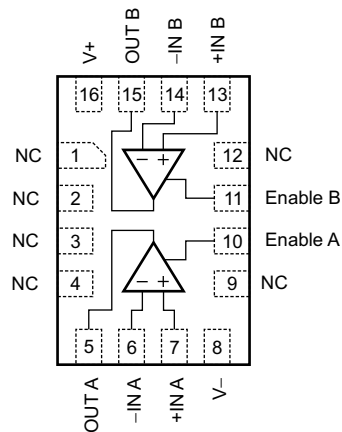
**OPA364: D PACKAGE
SO-8
(TOP VIEW)**



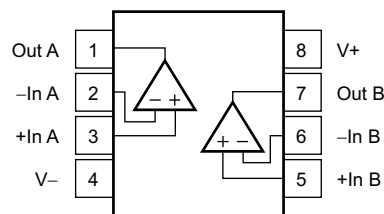
**OPA2363: DGS PACKAGE
MSOP-10
(TOP VIEW)**



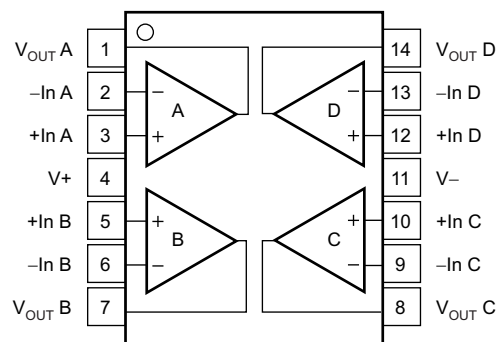
**OPA2363: RSV PACKAGE
UQFN-16
(TOP VIEW)**



**OPA2364: DGK, D PACKAGES
MSOP-8, SO-8
(TOP VIEW)**



**OPA4364: D, PW PACKAGES
SO-14, TSSOP-14
(TOP VIEW)**



(1) Orient according to marking.

NOTE: NC = No internal connection.

TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $R_L = 10\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, and $V_{CM} = V_S/2$, unless otherwise noted.

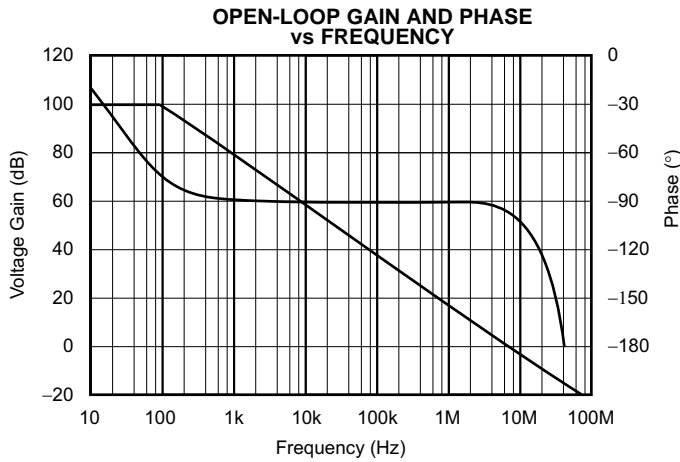


Figure 1.

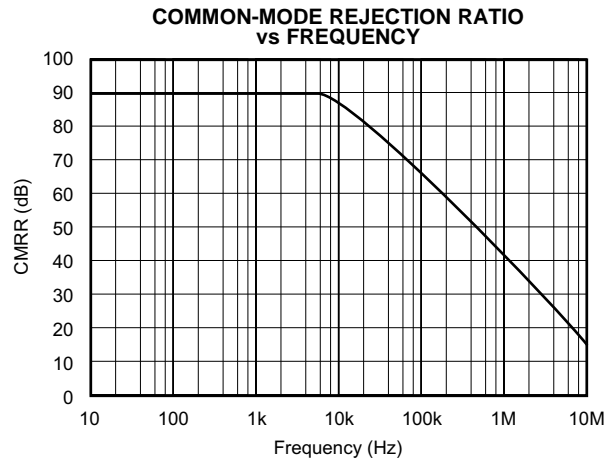


Figure 2.

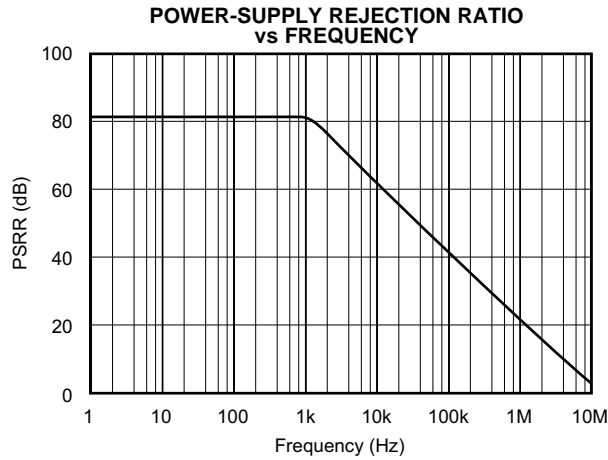


Figure 3.

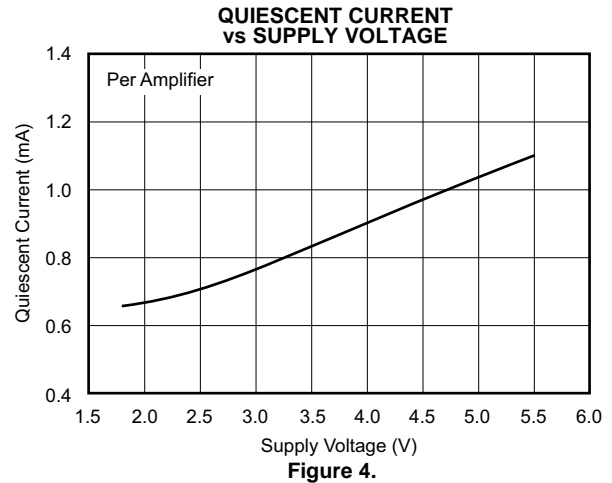


Figure 4.

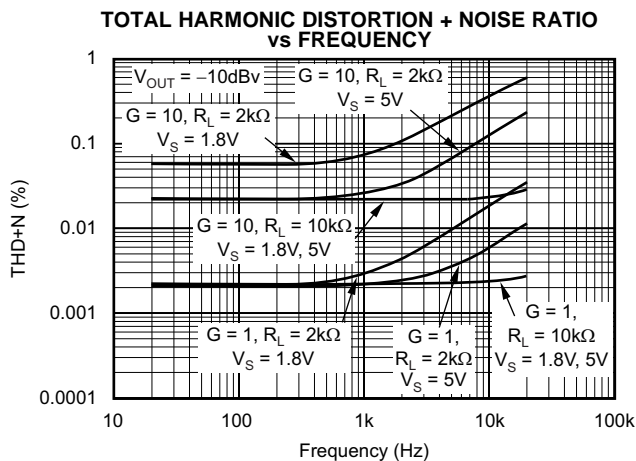


Figure 5.

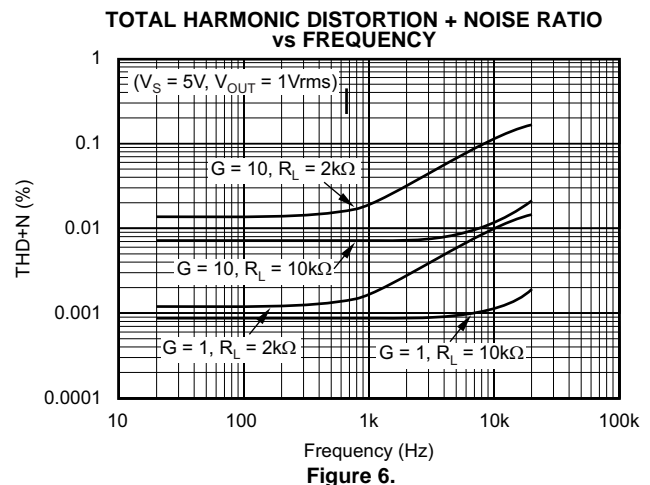
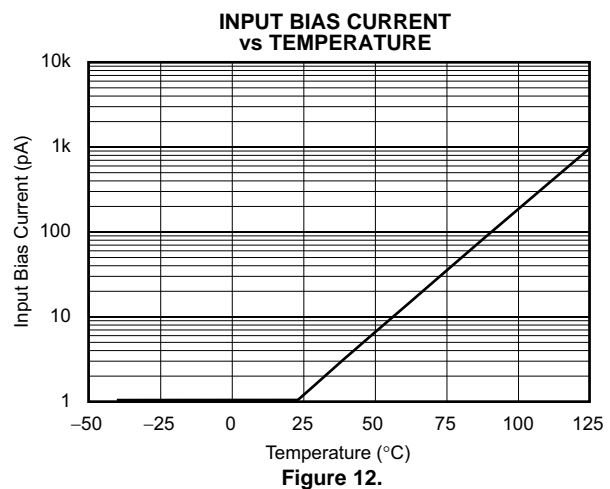
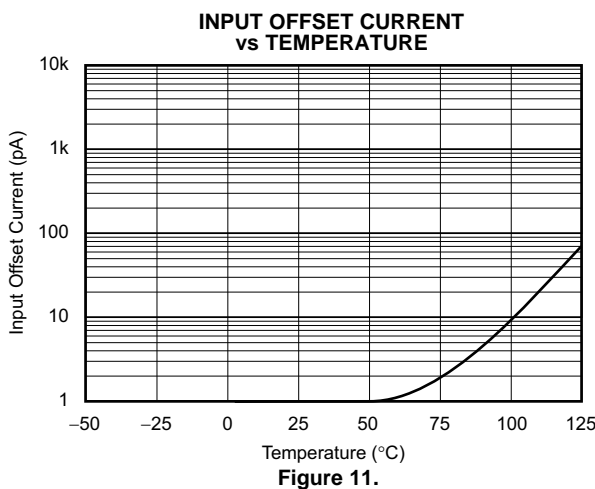
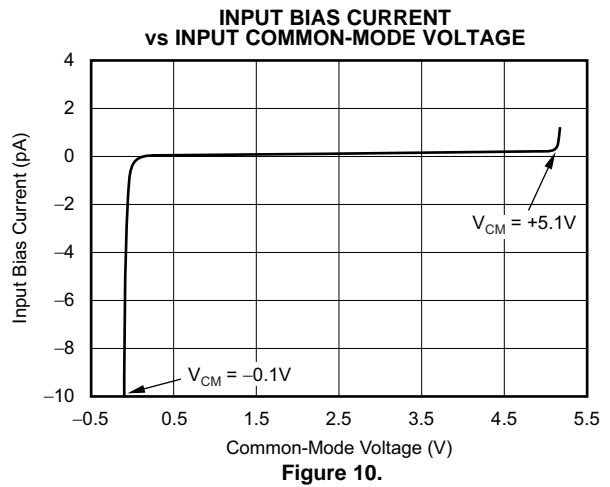
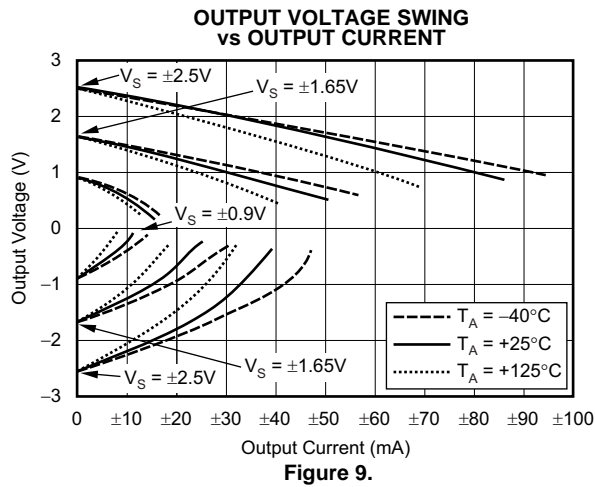
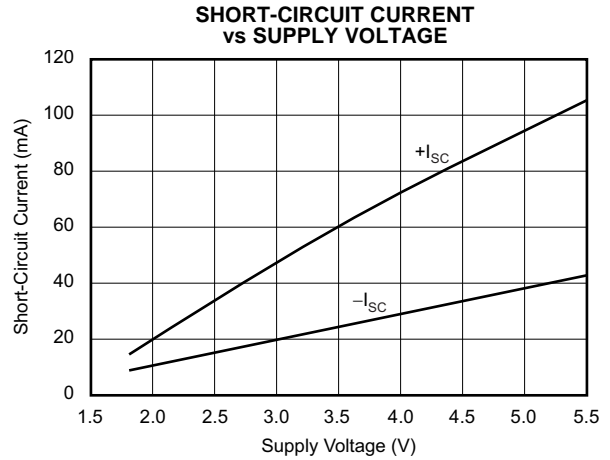
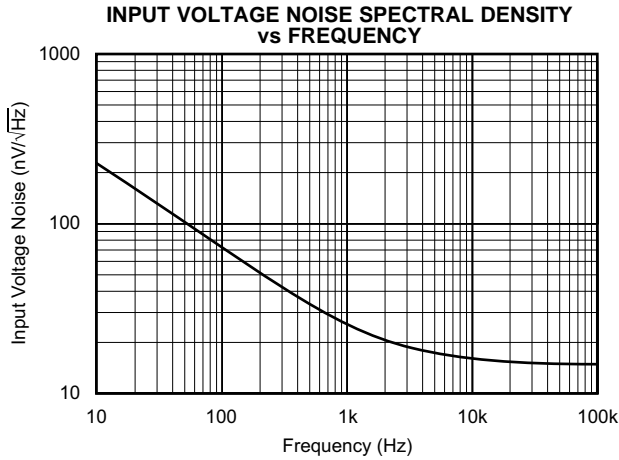


Figure 6.

TYPICAL CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, $R_L = 10\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, and $V_{CM} = V_S/2$, unless otherwise noted.



TYPICAL CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, $R_L = 10\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, and $V_{CM} = V_S/2$, unless otherwise noted.

SMALL-SIGNAL OVERSHOOT vs LOAD CAPACITANCE

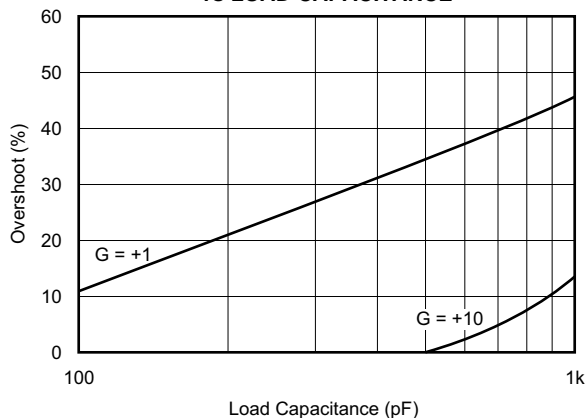


Figure 13.

SETTLING TIME vs CLOSED-LOOP GAIN

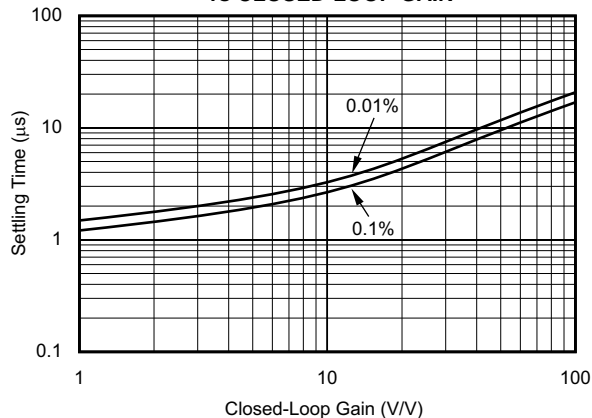


Figure 14.

OFFSET DRIFT DISTRIBUTION

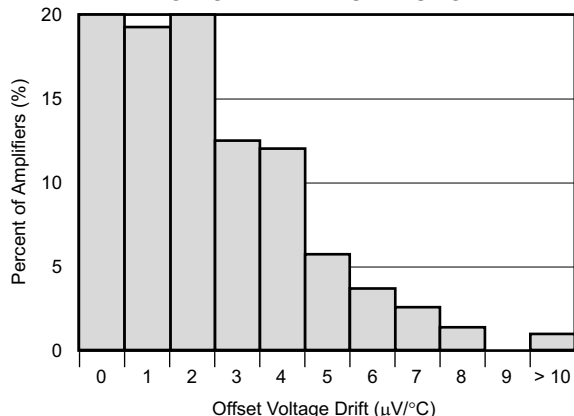


Figure 15.

OFFSET VOLTAGE PRODUCTION DISTRIBUTION

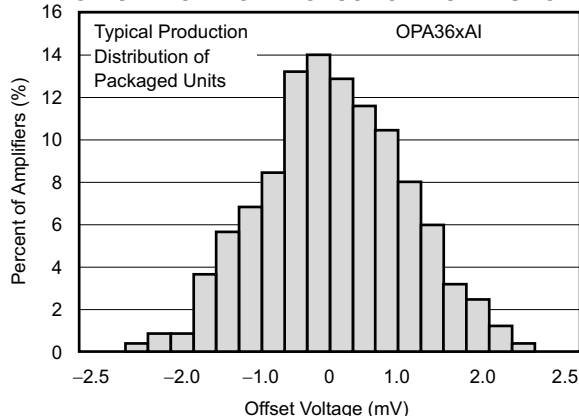


Figure 16.

OUTPUT ENABLE CHARACTERISTIC
($V_S = 5\text{V}$, $V_{OUT} = 20\text{kHz Sinusoid}$)

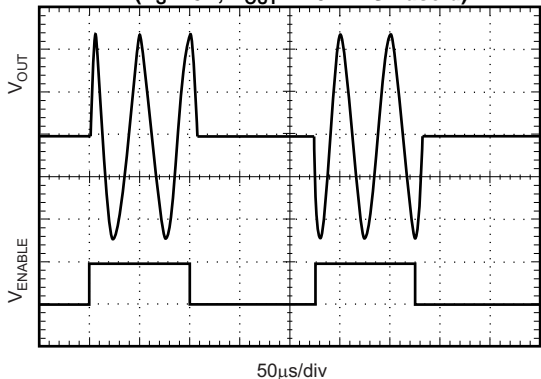


Figure 17.

CHANNEL SEPARATION vs FREQUENCY

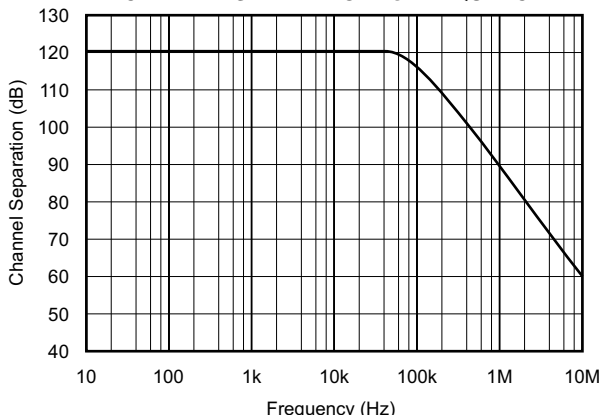
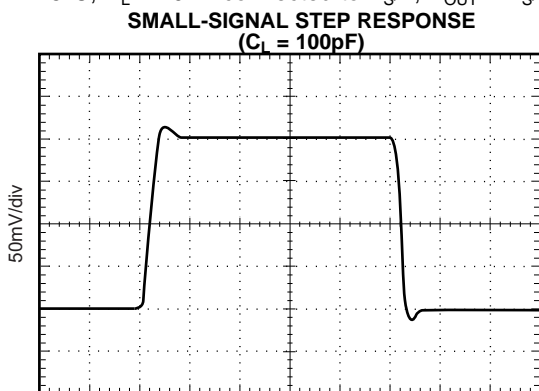


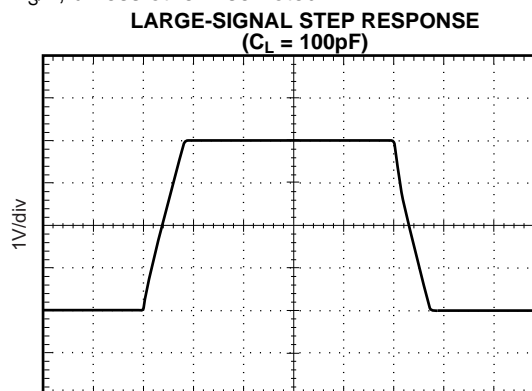
Figure 18.

TYPICAL CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, $R_L = 10\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, and $V_{CM} = V_S/2$, unless otherwise noted.



250ns/div
 Figure 19.



1µs/div
 Figure 20.

APPLICATION INFORMATION

The OPA363 and OPA364 series op amps are rail-to-rail operational amplifiers with excellent CMRR, low noise, low offset, and wide bandwidth on supply voltages as low as $\pm 0.9\text{V}$. The OPA363 features an additional pin for shutdown/ enable function. These families do not exhibit phase reversal and are unity-gain stable. Specified over the industrial temperature range of -40°C to $+125^\circ\text{C}$, the OPA363 and OPA364 families offer precision performance for a wide range of applications.

RAIL-TO-RAIL INPUT

The OPA363 and OPA364 feature excellent rail-to-rail operation, with supply voltages as low as $\pm 0.9\text{V}$. The input common-mode voltage range of the OPA363 and OPA364 family extends 100mV beyond supply rails. The unique input topology of the OPA363 and OPA364 eliminates the input offset transition region typical of most rail-to-rail complimentary stage operational amplifiers, allowing the OPA363 and OPA364 to provide superior common-mode performance over the entire common-mode input range, as seen in Figure 21. This feature prevents degradation of the differential linearity error and THD when driving A/D converters. A simplified schematic of the OPA363 and OPA364 is shown in Figure 22.

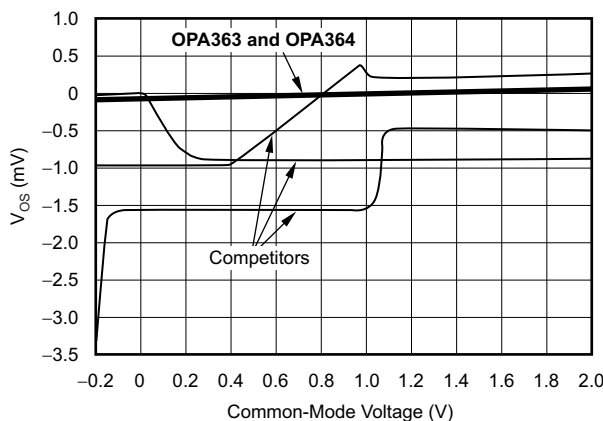


Figure 21. OPA363 and OPA364 have Linear Offset Over Entire Common-Mode Range

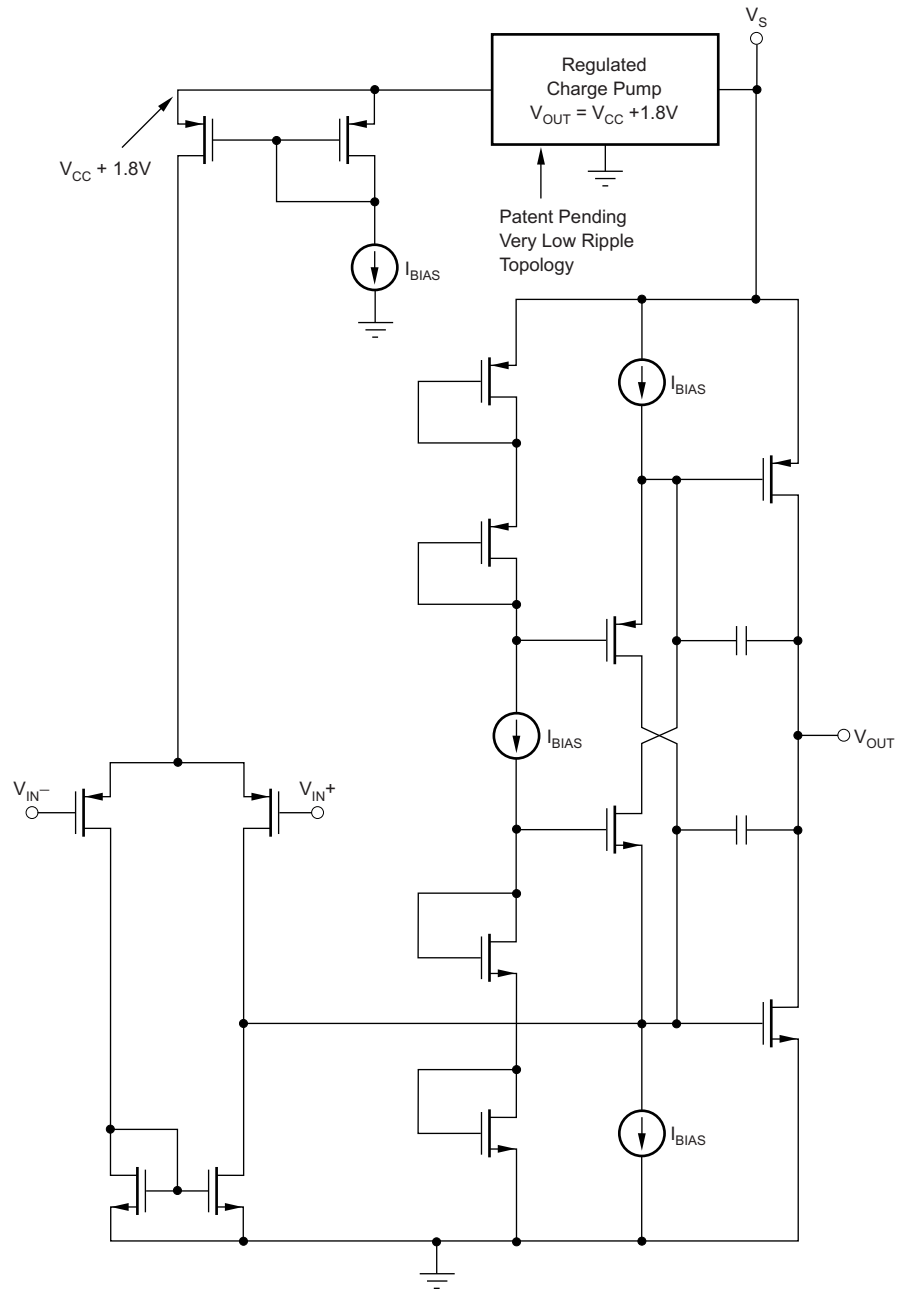


Figure 22. Simplified Schematic.

OPERATING VOLTAGE

The OPA363 and OPA364 series op amp parameters are fully specified from +1.8V to +5.5V. Single 0.1 μ F bypass capacitors should be placed across supply pins and as close to the part as possible. Supply voltages higher than 5.5V (absolute maximum) may cause permanent damage to the amplifier. Many specifications apply from -40°C to $+125^{\circ}\text{C}$. Parameters that vary significantly with operating voltages or temperature are shown in the [Typical Characteristics](#).

ENABLE FUNCTION

The shutdown (enable) function of the OPA363 is referenced to the negative supply voltage of the operational amplifier. A logic level HIGH enables the op amp. A valid logic HIGH is defined as voltage greater than 75% of the positive supply applied to the enable pin. The valid logic HIGH signal can be as much as 5.5V above the negative supply, independent of the positive supply voltage. A valid logic LOW is defined as less than 0.8V above the negative supply pin. If dual or split power supplies are used, care should be taken to ensure logic input signals are properly referred to the negative supply voltage. This pin should be connected to a valid high or low voltage or driven, not left open circuit.

The logic input is a high-impedance CMOS input. Dual op amps are provided separate logic inputs. For battery-operated applications, this feature may be used to greatly reduce the average current and extend battery life. The enable time is 20 μ s; disable time is 1 μ s. When disabled, the output assumes a high-impedance state. This allows the OPA363 to be operated as a “gated” amplifier, or to have its output multiplexed onto a common analog output bus.

CAPACITIVE LOAD

The OPA363 and OPA364 series op amps can drive a wide range of capacitive loads. However, all op amps under certain conditions may become unstable. Op amp configuration, gain, and load value are just a few of the factors to consider when determining stability. An op amp in unity-gain configuration is the most susceptible to the effects of capacitive load. The capacitive load reacts with the output resistance of the op amp to create a pole in the small-signal response, which degrades the phase margin.

In unity gain, the OPA363 and OPA364 series op amps perform well with a pure capacitive load up to approximately 1000pF. The ESR (Equivalent Series Resistance) of the loading capacitor may be sufficient to allow the OPA363 and OPA364 to directly drive very large capacitive loads ($> 1\mu\text{F}$). Increasing gain enhances the amplifier’s ability to drive more capacitance; see [Figure 13](#).

One method of improving capacitive load drive in the unity-gain configuration is to insert a 10 Ω to 20 Ω resistor in series with the output, as shown in [Figure 23](#). This significantly reduces ringing with large capacitive loads. However, if there is a resistive load in parallel with the capacitive load, it creates a voltage divider introducing a dc error at the output and slightly reduces output swing. This error may be insignificant. For instance, with $R_L = 10\text{k}\Omega$ and $R_S = 20\Omega$, there is only about a 0.2% error at the output.

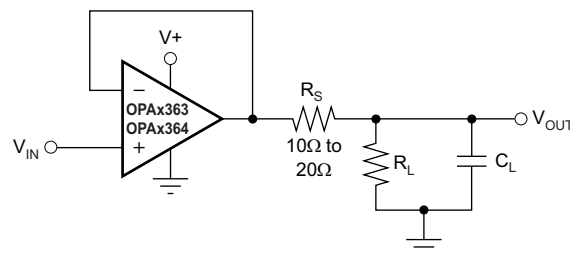


Figure 23. Improving Capacitive Load Drive

INPUT AND ESD PROTECTION

All OPA363 and OPA364 pins are static protected with internal ESD protection diodes tied to the supplies. These diodes will provide overdrive protection if the current is externally limited to 10mA, as stated in the absolute maximum ratings and shown in Figure 24.

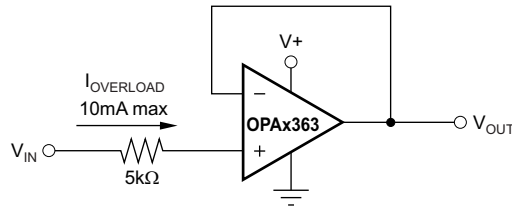


Figure 24. Input Current Protection

ACHIEVING OUTPUT SWING TO THE OP AMP'S NEGATIVE RAIL

Some applications require an accurate output voltage swing from 0V to a positive full-scale voltage. A good single supply op amp may be able to swing within a few mV of single supply ground, but as the output is driven toward 0V, the output stage of the amplifier will prevent the output from reaching the negative supply rail of the amplifier.

The output of the OPA363 or OPA364 can be made to swing to ground, or slightly below, on a single supply power source. To do so requires use of another resistor and an additional, more negative power supply than the op amp's negative supply. A pull-down resistor may be connected between the output and the additional negative supply to pull the output down below the value that the output would otherwise achieve as shown in Figure 25.

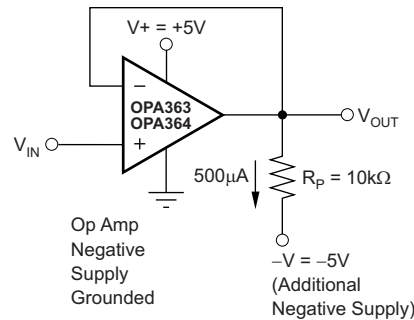


Figure 25. OPA363 and OPA364 Swing to Ground

This technique will not work with all op amps. The output stage of the OPA363 and OPA364 allows the output voltage to be pulled below that of most op amps, if approximately 500μA is maintained through the output stage. To calculate the appropriate value load resistor and negative supply, $R_L = -V/500\mu A$. The OPA363 and OPA364 have been characterized to perform well under the described conditions, maintaining excellent accuracy down to 0V and as low as -10mV. Limiting and nonlinearity occur below -10mV, with linearity returning as the output is again driven above -10mV.

BUFFERED REFERENCE VOLTAGE

Many single-supply applications require a mid-supply reference voltage. The OPA363 and OPA364 offer excellent capacitive load drive capability, and can be configured to provide a 0.9V reference voltage, as can be seen in Figure 26. For appropriate loading considerations, see the CAPACITIVE LOAD section.

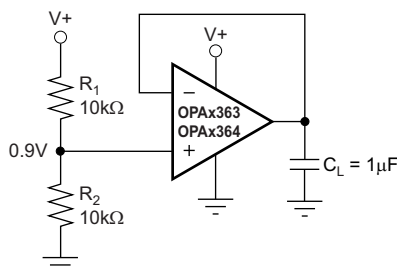


Figure 26. The OPA363 and OPA364 Provide a Stable Reference Voltage

DIRECTLY DRIVING THE ADS8324 AND THE MSP430

The OPA363 and OPA364 series op amps are optimized for driving medium speed (up to 100kHz) sampling A/D converters. However, they also offer excellent performance for higher speed converters. The no crossover input stage of the OPA363 and OPA364 directly drive A/D converters without degradation of differential linearity and THD. They provide an effective means of buffering the A/D converters input capacitance and resulting charge injection while providing signal gain. Figure 27 and Figure 28 show the OPA363 and OPA364 configured to drive the ADS8324 and the 12-bit A/D converter on the MSP430.

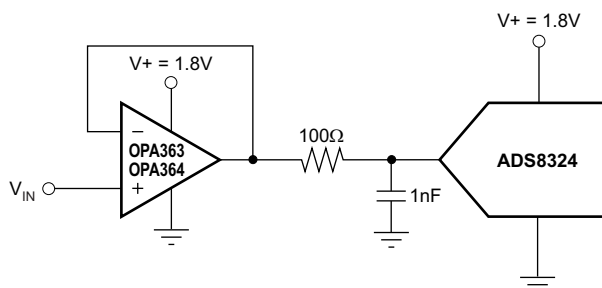


Figure 27. The OPA363 and OPA364 Directly Drive the ADS8324

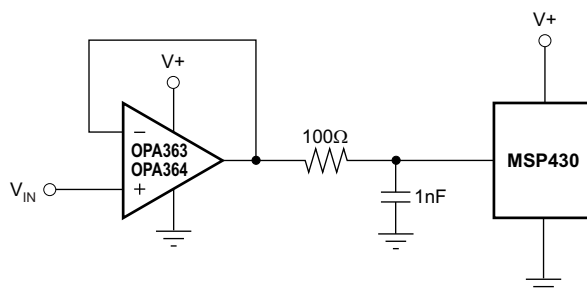


Figure 28. Driving the 12-Bit A/D Converter on the MSP430

AUDIO APPLICATIONS

The OPA363 and OPA364 op amp family has linear offset voltage over the entire input common-mode range. Combined with low-noise, this feature makes the OPA363 and OPA364 suitable for audio applications. Single supply 1.8V operation allows the OPA2363 and OPA2364 to be optimal candidates for dual stereo-headphone drivers and microphone pre-amplifiers in portable stereo equipment, see [Figure 29](#) and [Figure 30](#).

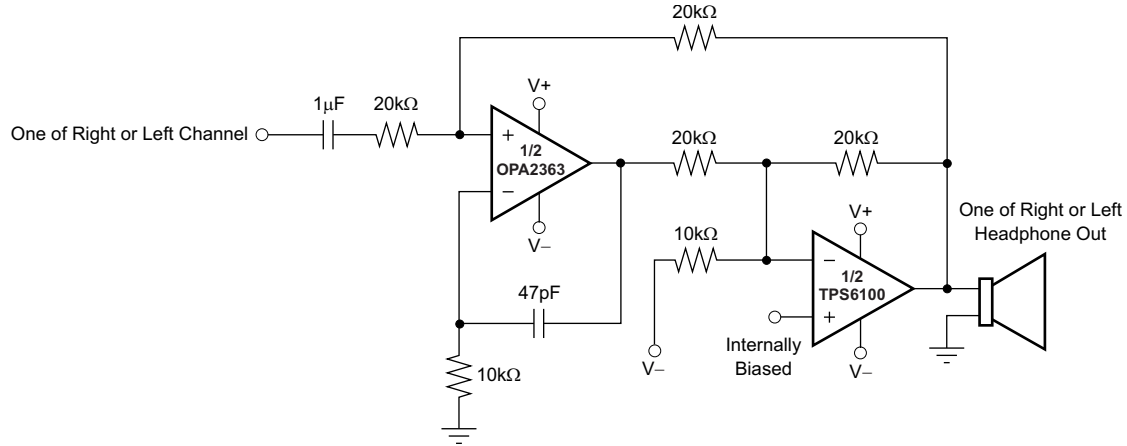


Figure 29. OPA2363 Configured as Half of a Dual Stereo Headphone Driver

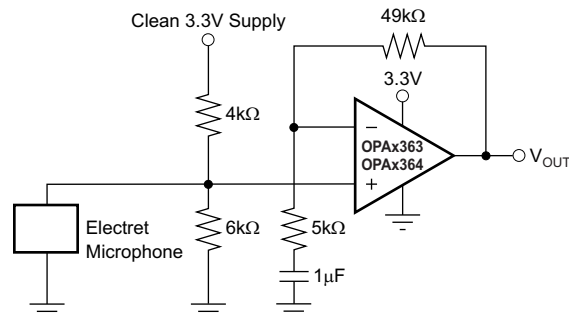


Figure 30. Microphone Preamplifier

ACTIVE FILTERING

Low harmonic distortion and noise specifications plus high gain and slew rate make the OPA363 and OPA364 optimal candidates for active filtering. Figure 31 shows the OPA2363 configured as a low-distortion, 3rd-order GIC (General Immittance Converter) filter. Figure 32 shows the implementation of a Sallen-Key, 3-pole, low-pass Bessel filter.

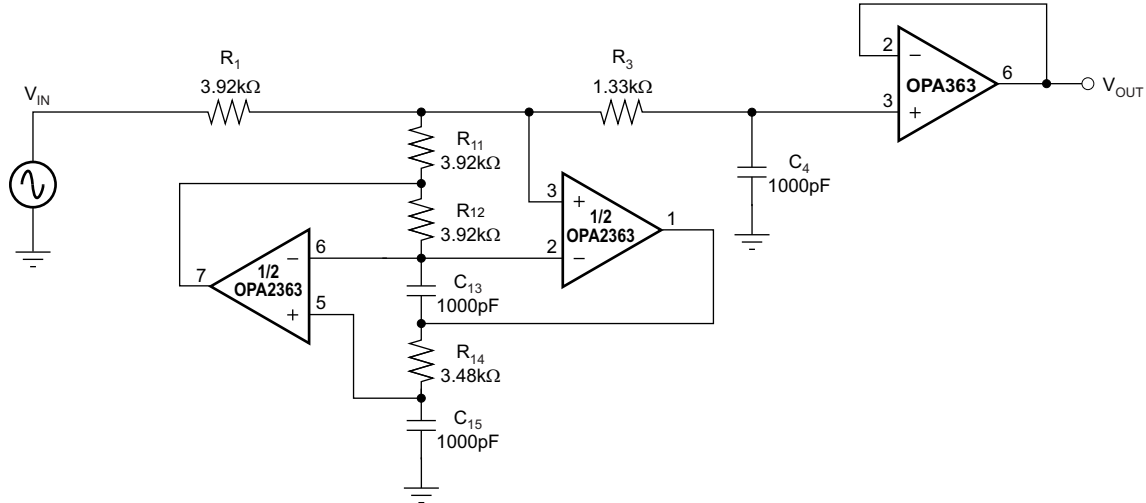


Figure 31. The OPA2363 as a 3rd-Order, 40kHz, Low-Pass GIC Filter

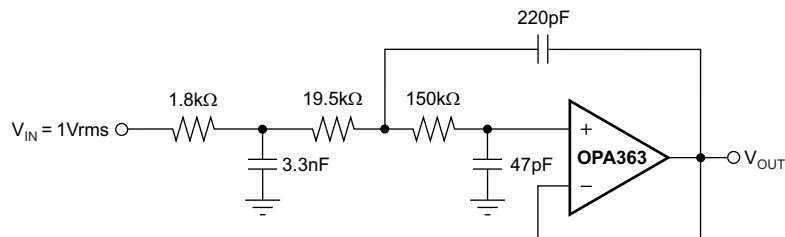


Figure 32. The OPA363 or OPA364 Configured as a 3-Pole, 20kHz, Sallen-Key Filter

REVISION HISTORY

NOTE: Page numbers for previous versions may differ from page numbers in the current version.

| Changes from Revision B (February 2003) to Revision C | Page |
|--|-------------|
| • Converted data sheet to current format | 1 |
| • Added RSV package (UQFN-16) to data sheet | 1 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| OPA2363AIDGSR | ACTIVE | VSSOP | DGS | 10 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHK | Samples |
| OPA2363AIDGST | ACTIVE | VSSOP | DGS | 10 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHK | Samples |
| OPA2363AIDGSTG4 | ACTIVE | VSSOP | DGS | 10 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHK | Samples |
| OPA2363AIRSVR | ACTIVE | UQFN | RSV | 16 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | SIN | Samples |
| OPA2363IDGSR | ACTIVE | VSSOP | DGS | 10 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHK | Samples |
| OPA2363IDGST | ACTIVE | VSSOP | DGS | 10 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHK | Samples |
| OPA2363IDGSTG4 | ACTIVE | VSSOP | DGS | 10 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHK | Samples |
| OPA2364AID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 2364 A | Samples |
| OPA2364AIDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 2364 A | Samples |
| OPA2364AIDGKR | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHL | Samples |
| OPA2364AIDGKRG4 | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHL | Samples |
| OPA2364AIDGKT | ACTIVE | VSSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHL | Samples |
| OPA2364AIDGKTG4 | ACTIVE | VSSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHL | Samples |
| OPA2364AIDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 2364 A | Samples |
| OPA2364AIDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 2364 A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| OPA2364ID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 2364 | Samples |
| OPA2364IDG4 | ACTIVE | SOIC | D | 8 | | TBD | Call TI | Call TI | -40 to 125 | | Samples |
| OPA2364IDGKR | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHL | Samples |
| OPA2364IDGKRG4 | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHL | Samples |
| OPA2364IDGKT | ACTIVE | VSSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHL | Samples |
| OPA2364IDGKTG4 | ACTIVE | VSSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | BHL | Samples |
| OPA2364IDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 2364 | Samples |
| OPA2364IDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 2364 | Samples |
| OPA363AID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 363 A | Samples |
| OPA363AIDBVR | ACTIVE | SOT-23 | DBV | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A40 | Samples |
| OPA363AIDBVRG4 | ACTIVE | SOT-23 | DBV | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A40 | Samples |
| OPA363AIDBVT | ACTIVE | SOT-23 | DBV | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A40 | Samples |
| OPA363AIDBVTG4 | ACTIVE | SOT-23 | DBV | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A40 | Samples |
| OPA363ID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 363 | Samples |
| OPA363IDBVR | ACTIVE | SOT-23 | DBV | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A40 | Samples |
| OPA363IDBVRG4 | ACTIVE | SOT-23 | DBV | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A40 | Samples |
| OPA363IDBVT | ACTIVE | SOT-23 | DBV | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A40 | Samples |
| OPA363IDBVTG4 | ACTIVE | SOT-23 | DBV | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A40 | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| OPA363IDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 363 | Samples |
| OPA364AID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 364 A | Samples |
| OPA364AIDBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A41 | Samples |
| OPA364AIDBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A41 | Samples |
| OPA364AIDBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A41 | Samples |
| OPA364AIDBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A41 | Samples |
| OPA364AIDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 364 A | Samples |
| OPA364ID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 364 | Samples |
| OPA364IDBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A41 | Samples |
| OPA364IDBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A41 | Samples |
| OPA364IDBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A41 | Samples |
| OPA364IDBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | A41 | Samples |
| OPA364IDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 364 | Samples |
| OPA364IDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 364 | Samples |
| OPA364IDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 364 | Samples |
| OPA4364AID | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA4364A | Samples |
| OPA4364AIDG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA4364A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| OPA4364AIDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA4364A | Samples |
| OPA4364AIDRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA4364A | Samples |
| OPA4364AIPWR | ACTIVE | TSSOP | PW | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 4364A | Samples |
| OPA4364AIPWRG4 | ACTIVE | TSSOP | PW | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 4364A | Samples |
| OPA4364AIPWT | ACTIVE | TSSOP | PW | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 4364A | Samples |
| OPA4364AIPWTG4 | ACTIVE | TSSOP | PW | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | OPA 4364A | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF OPA4364 :

- Automotive: [OPA4364-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION



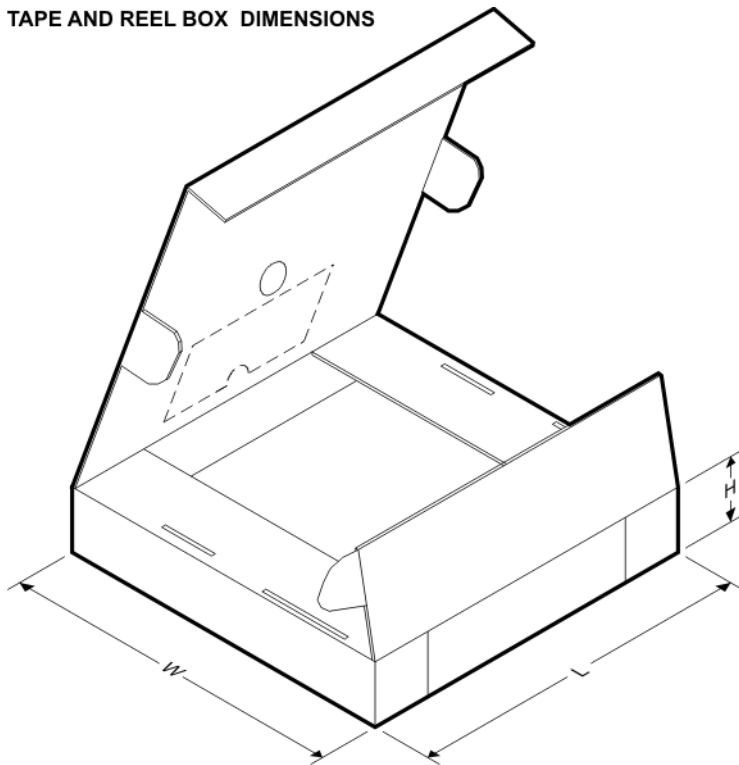
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| OPA2363AIDGSR | VSSOP | DGS | 10 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| OPA2363AIDGST | VSSOP | DGS | 10 | 250 | 180.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| OPA2363AIRSVR | UQFN | RSV | 16 | 3000 | 177.8 | 12.4 | 2.0 | 2.8 | 0.7 | 4.0 | 12.0 | Q1 |
| OPA2363IDGSR | VSSOP | DGS | 10 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| OPA2363IDGST | VSSOP | DGS | 10 | 250 | 180.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| OPA2364AIDGKR | VSSOP | DGK | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| OPA2364AIDGKT | VSSOP | DGK | 8 | 250 | 180.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| OPA2364AIDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| OPA2364IDGKR | VSSOP | DGK | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| OPA2364IDGKT | VSSOP | DGK | 8 | 250 | 180.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| OPA2364IDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| OPA363AIDBVR | SOT-23 | DBV | 6 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| OPA363AIDBVT | SOT-23 | DBV | 6 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| OPA363IDBVR | SOT-23 | DBV | 6 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| OPA363IDBVT | SOT-23 | DBV | 6 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| OPA364AIDBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.1 | 1.39 | 4.0 | 8.0 | Q3 |
| OPA364AIDBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 8.4 | 3.2 | 3.1 | 1.39 | 4.0 | 8.0 | Q3 |
| OPA364AIDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| OPA364IDBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.1 | 1.39 | 4.0 | 8.0 | Q3 |
| OPA364IDBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 8.4 | 3.2 | 3.1 | 1.39 | 4.0 | 8.0 | Q3 |
| OPA364IDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| OPA4364AIDR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| OPA4364AIPWR | TSSOP | PW | 14 | 2500 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| OPA4364AIPWT | TSSOP | PW | 14 | 250 | 180.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| OPA2363AIDGSR | VSSOP | DGS | 10 | 2500 | 367.0 | 367.0 | 35.0 |
| OPA2363AIDGST | VSSOP | DGS | 10 | 250 | 210.0 | 185.0 | 35.0 |
| OPA2363AIRSVR | UQFN | RSV | 16 | 3000 | 223.0 | 270.0 | 35.0 |
| OPA2363IDGSR | VSSOP | DGS | 10 | 2500 | 367.0 | 367.0 | 35.0 |
| OPA2363IDGST | VSSOP | DGS | 10 | 250 | 210.0 | 185.0 | 35.0 |
| OPA2364AIDGKR | VSSOP | DGK | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| OPA2364AIDGKT | VSSOP | DGK | 8 | 250 | 210.0 | 185.0 | 35.0 |
| OPA2364AIDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| OPA2364IDGKR | VSSOP | DGK | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| OPA2364IDGKT | VSSOP | DGK | 8 | 250 | 210.0 | 185.0 | 35.0 |
| OPA2364IDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| OPA363AIDBVR | SOT-23 | DBV | 6 | 3000 | 565.0 | 140.0 | 75.0 |
| OPA363AIDBVT | SOT-23 | DBV | 6 | 250 | 565.0 | 140.0 | 75.0 |
| OPA363IDBVR | SOT-23 | DBV | 6 | 3000 | 565.0 | 140.0 | 75.0 |
| OPA363IDBVT | SOT-23 | DBV | 6 | 250 | 565.0 | 140.0 | 75.0 |
| OPA364AIDBVR | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| OPA364AIDBVT | SOT-23 | DBV | 5 | 250 | 210.0 | 185.0 | 35.0 |
| OPA364AIDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| OPA364IDBVR | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| OPA364IDBVT | SOT-23 | DBV | 5 | 250 | 210.0 | 185.0 | 35.0 |
| OPA364IDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| OPA4364AIDR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| OPA4364AIPWR | TSSOP | PW | 14 | 2500 | 367.0 | 367.0 | 35.0 |
| OPA4364AIPWT | TSSOP | PW | 14 | 250 | 210.0 | 185.0 | 35.0 |

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

MECHANICAL DATA

DBV (R-PDSO-G6)

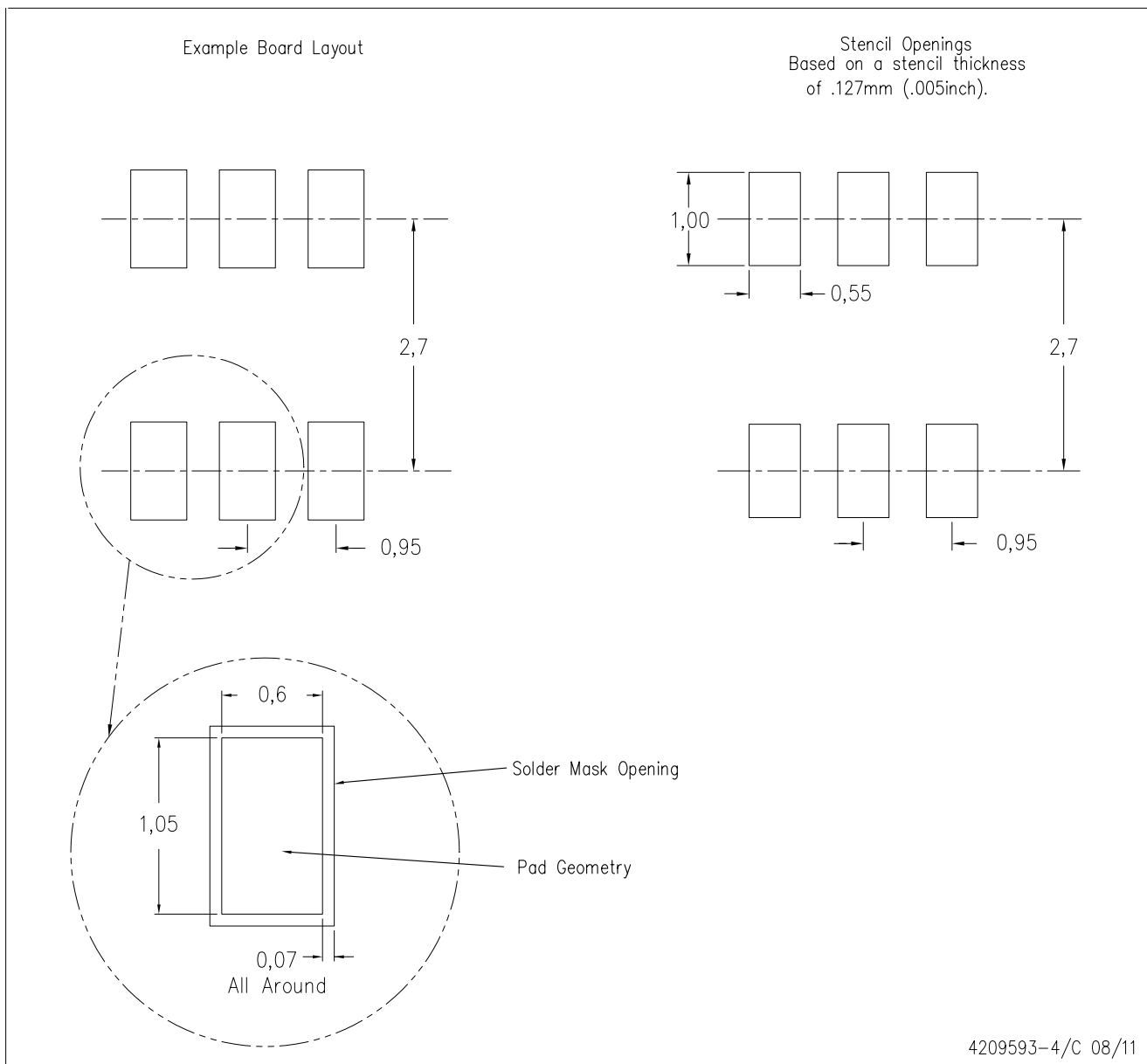
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.

DBV (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
 - E. Falls within JEDEC MO-187 variation AA, except interlead flash.



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DGS (S-PDSO-G10)

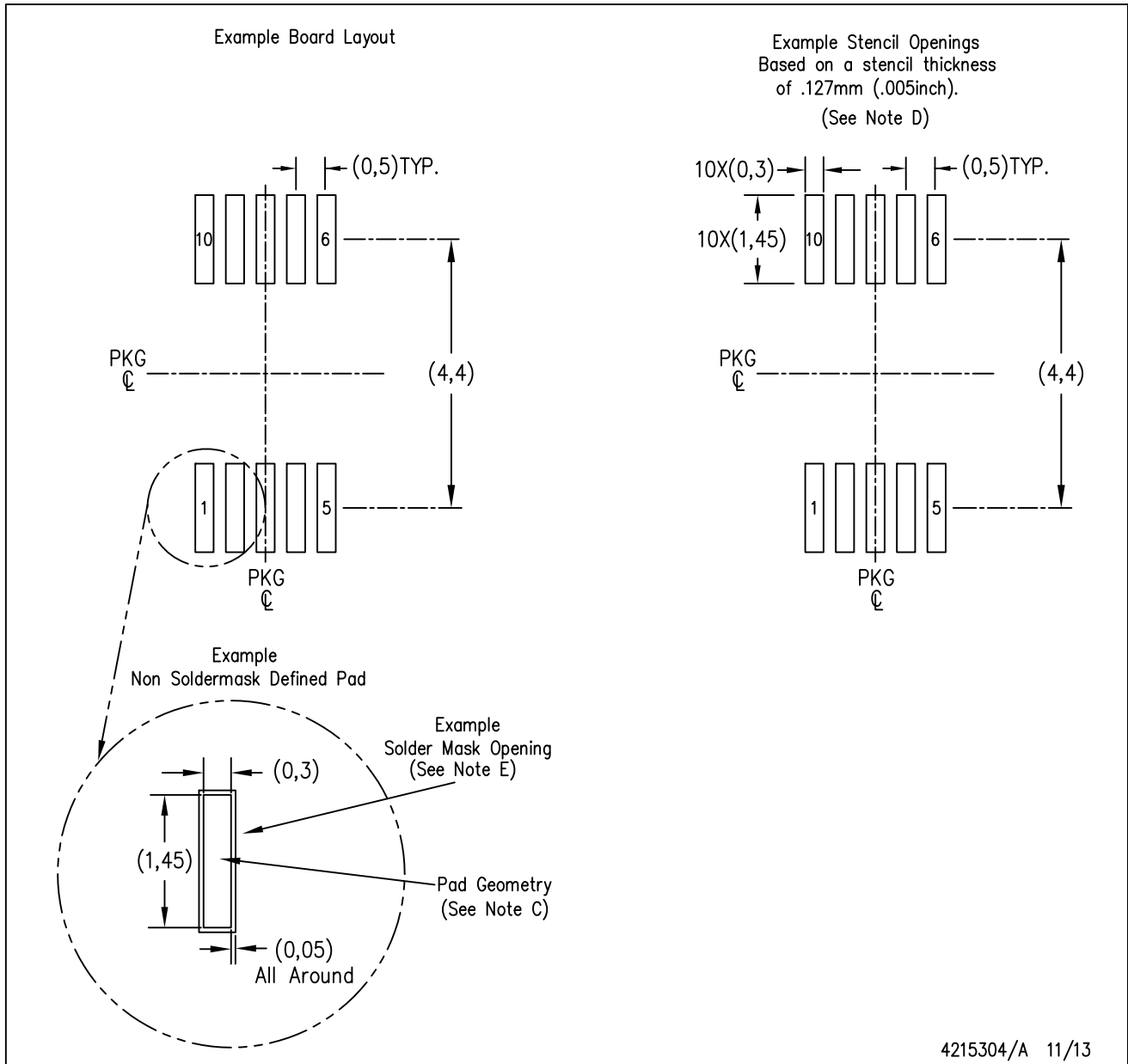
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion.
 - D. Falls within JEDEC MO-187 variation BA.

DGS (S-PDSO-G10)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

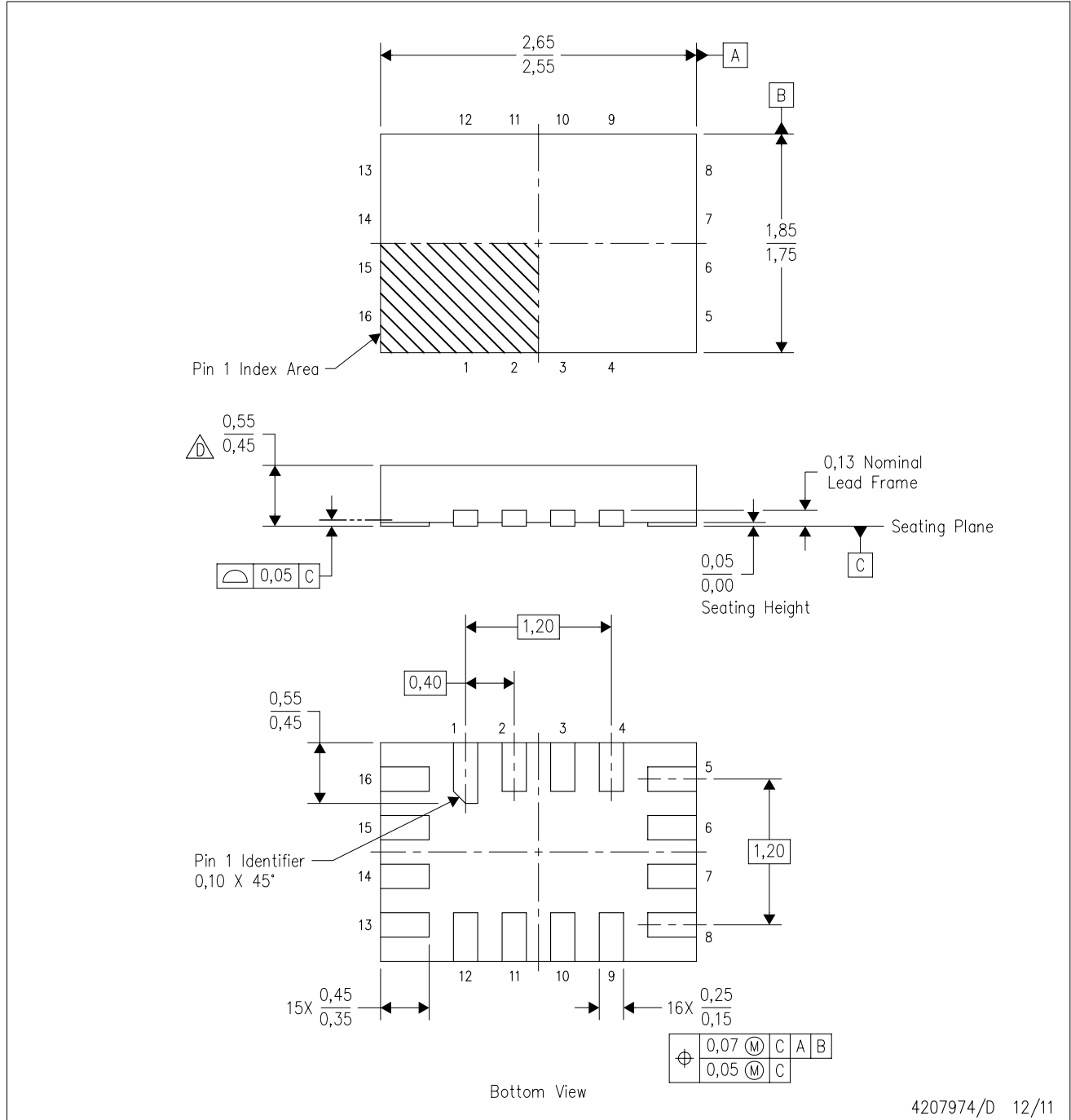
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

RSV (R-PUQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD

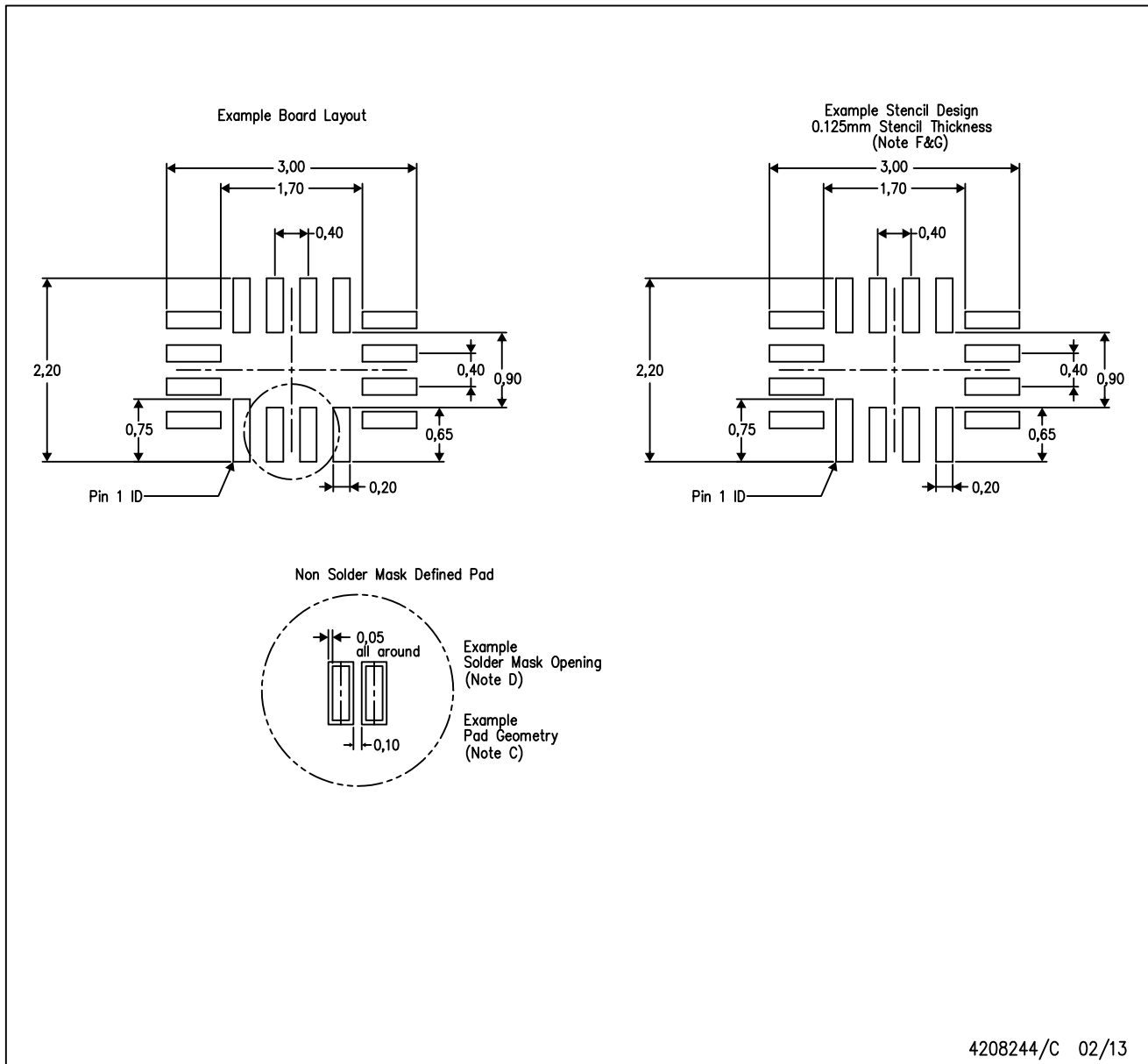


4207974/D 12/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - This package complies to JEDEC MO-288 variation UFHE, except minimum package thickness.

RSV (R-PUQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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